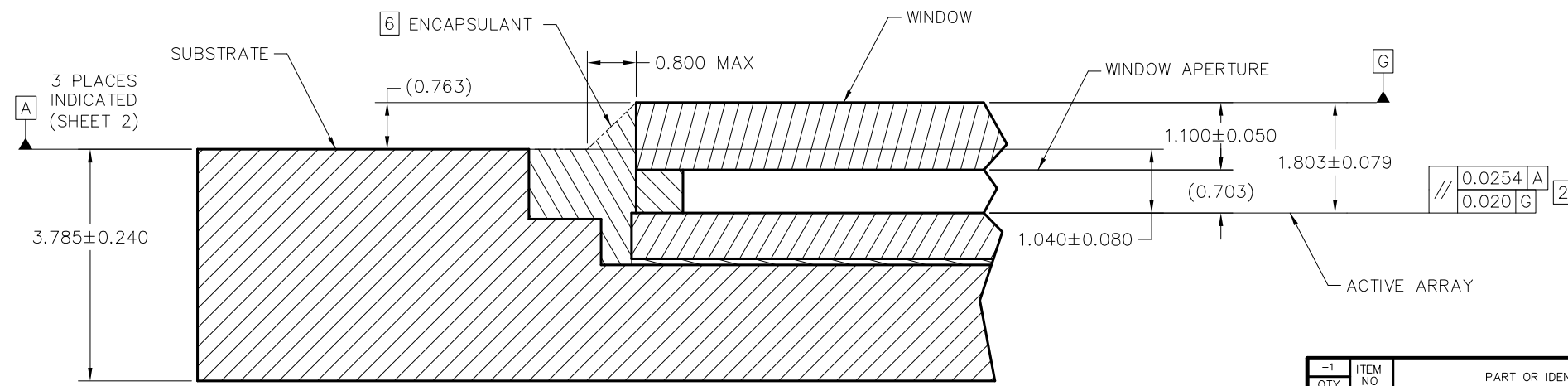
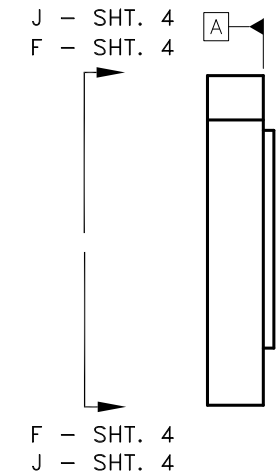
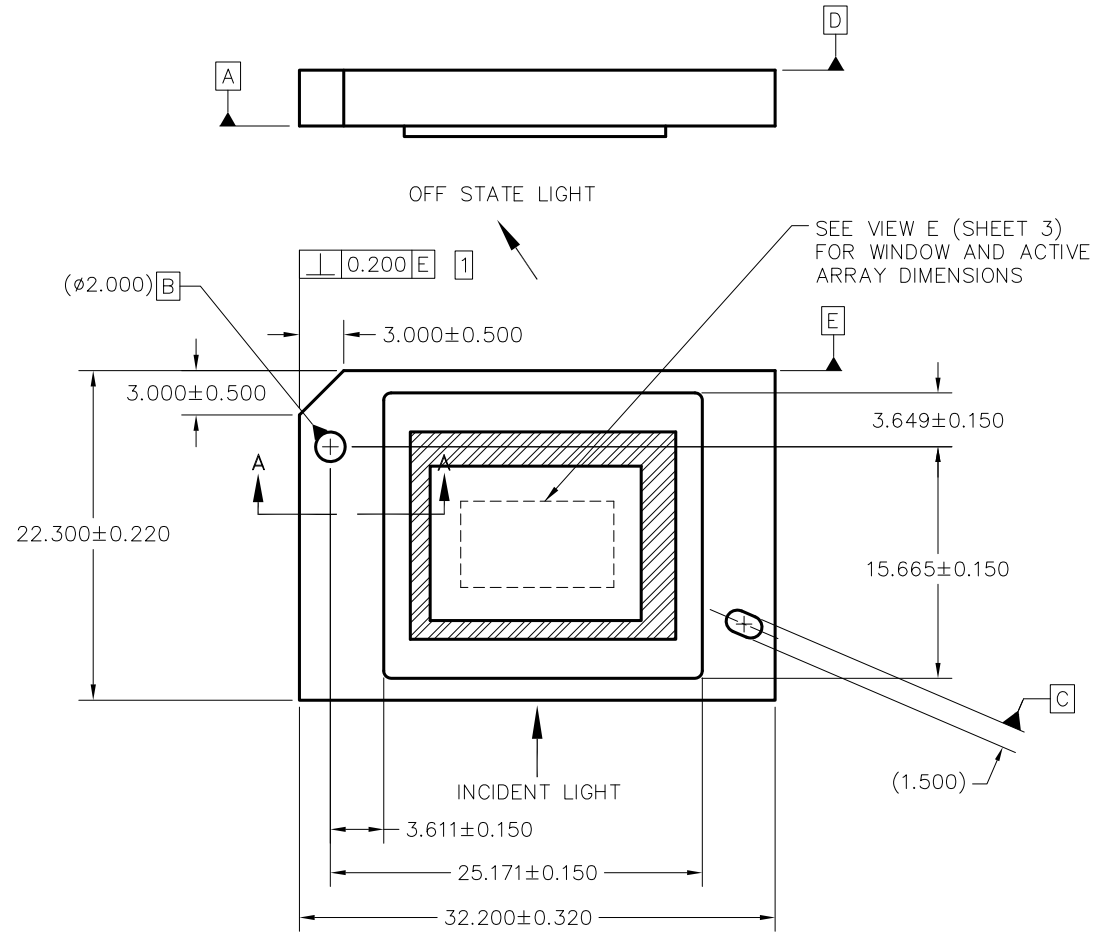


REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
A	ECO 2159771, INITIAL RELEASE	07/28/2016	F. ARMSTRONG
B	ECO 2163097, CORRECT POM Y-DIRECTION DIMS	12/15/2016	F. ARMSTRONG

NOTES: UNLESS OTHERWISE SPECIFIED:

- 1 SUBSTRATE EDGE PERPENDICULARITY TOLERANCE APPLIES TO ENTIRE SURFACE
- 2 DIE PARALLELISM TOLERANCE APPLIES TO DMD ACTIVE ARRAY ONLY
- 3 ROTATION ANGLE OF DMD ACTIVE ARRAY IS A REFINEMENT OF THE LOCATION TOLERANCE AND HAS A MAXIMUM ALLOWED VALUE OF 0.8 DEGREES
- 4 SUBSTRATE SYMBOLIZATION PAD, AND PLATING AT BOTTOM OF DATUMS B AND C HOLES TO BE ELECTRICALLY CONNECTED TO VSS PLANE WITHIN THE SUBSTRATE
- 5 BOUNDARY MIRRORS SURROUNDING THE DMD ACTIVE AREA
- 6 MAXIMUM ENCAPSULANT PROFILE SHOWN
- 7 ENCAPSULANT ALLOWED ON THE SURFACE OF THE CERAMIC IN THE AREA SHOWN IN VIEW B (SHEET 2). ENCAPSULANT SHALL NOT EXCEED 0.200 THICKNESS MAXIMUM.
- 8 SUBSTRATES PLATED WITH Ni/Au SHALL HAVE THE THREE-DIGIT NUMERICAL MARKING IN THE AREA TO THE LEFT OF THE SYMBOLIZATION PAD. SUBSTRATES PLATED WITH Ni/Pd/Au SHALL HAVE THE MARKING IN THE AREA TO THE RIGHT OF THE SYMBOLIZATION PAD.

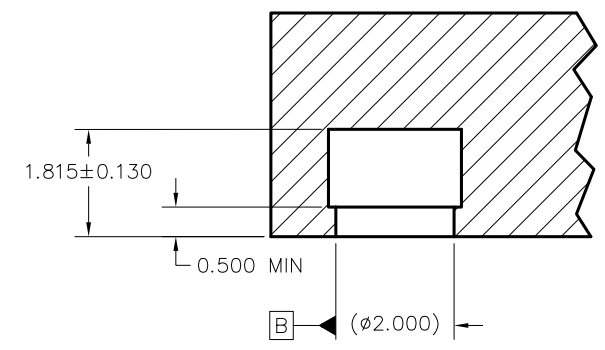
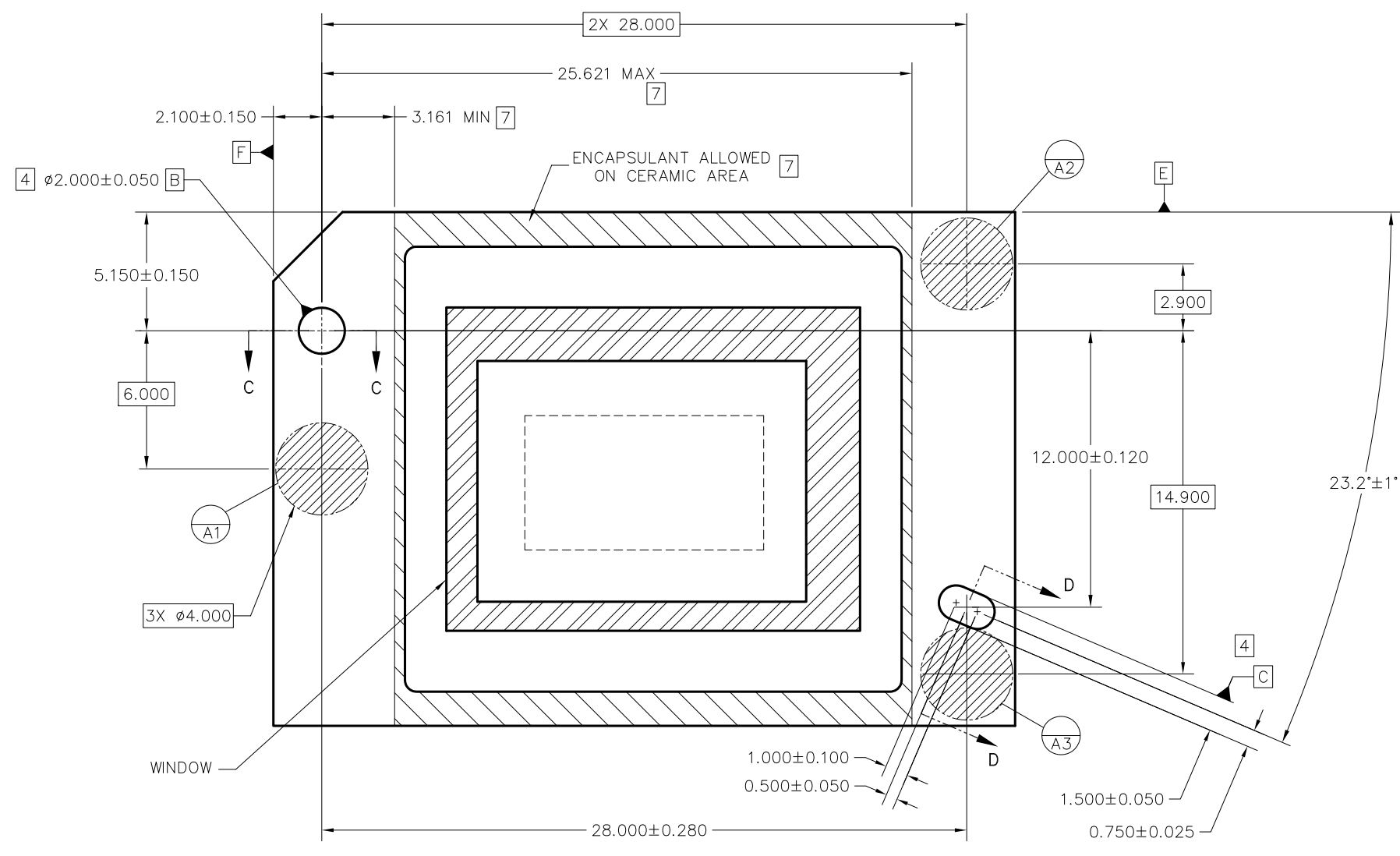
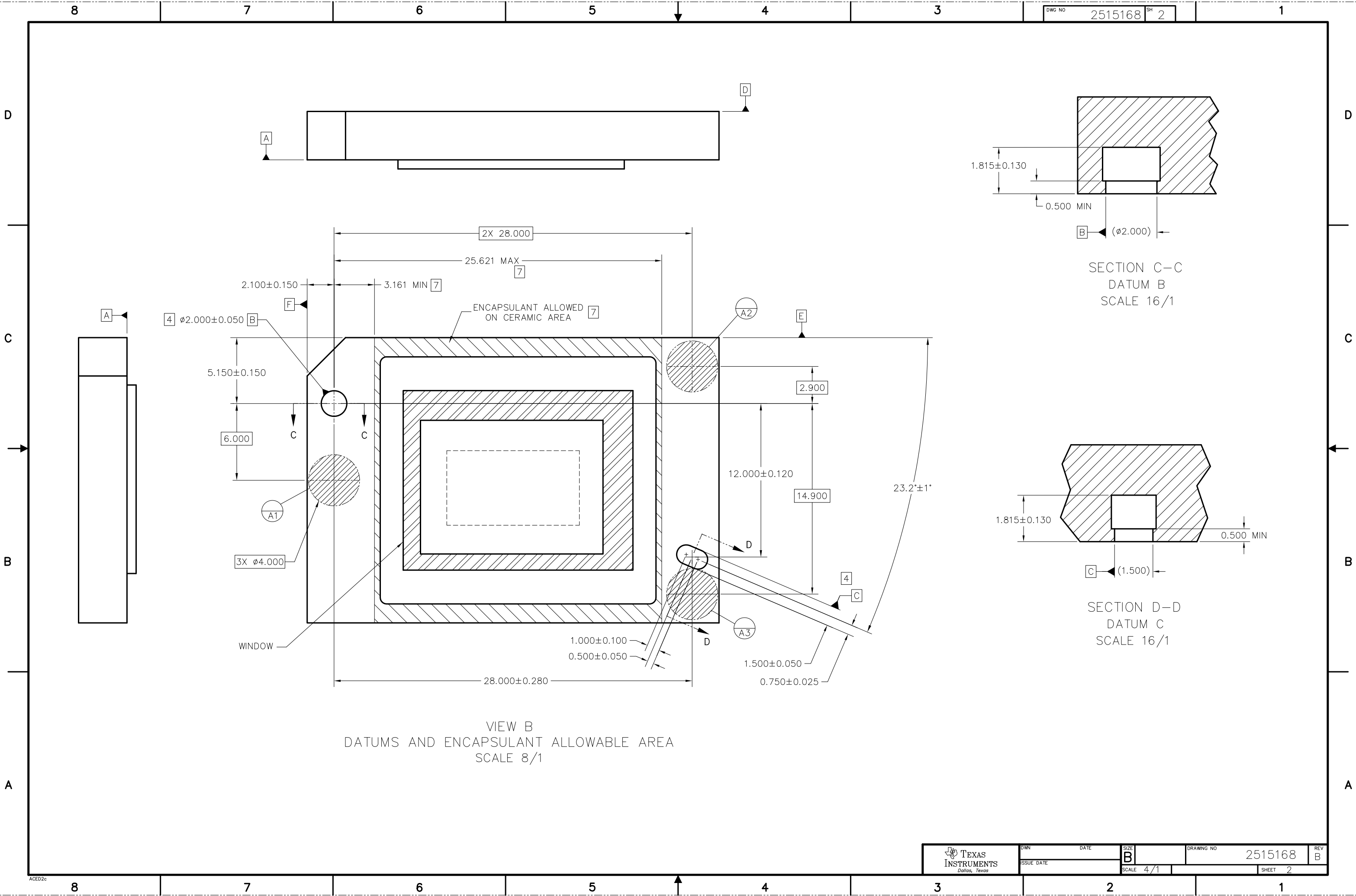


SECTION A-A
SCALE 20/1

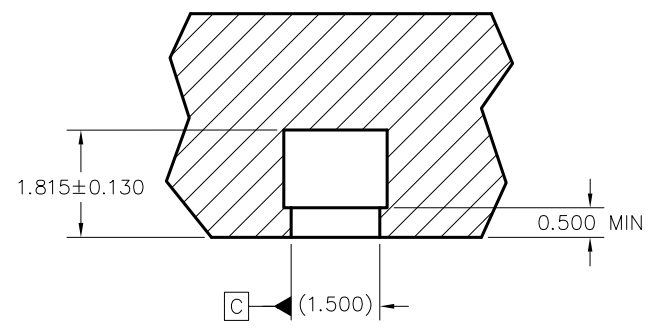
QTY	ITEM NO	PART OR IDENTIFYING NUMBER	NOMENCLATURE OR DESCRIPTION	NOTES
-1				

PARTS LIST		DATE		DRAWN	
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS TOLERANCES: ANGLES ± 1° 2 PLACE DECIMALS ±0.25 3 PLACE DECIMALS ±0.50		07/13/16		F. ARMSTRONG	
REMOVE ALL BURRS AND SHARP EDGES INTERPRET DIMENSIONS IN ACCORDANCE WITH ASME Y14.5-1994 DIMENSIONAL LIMITS APPLY BEFORE PROCESSES PARENTHEICAL INFO FOR REF ONLY		07/13/16		F. ARMSTRONG	
		08/03/16		P. KONRAD	
		08/03/16		M. DORAK	

ICD, MECHANICAL, DMD .47" 1080p MTRP 2xLVDS HB SERIES 410 (FXH PACKAGE)		DRAWING NO 2515168		REV B	
SCALE 4/1		SHEET 1 OF 4			



SECTION C-C
DATUM B
SCALE 16/1



SECTION D-D
DATUM C
SCALE 16/1

VIEW B
DATUMS AND ENCAPSULANT ALLOWABLE AREA
SCALE 8/1

8

7

6

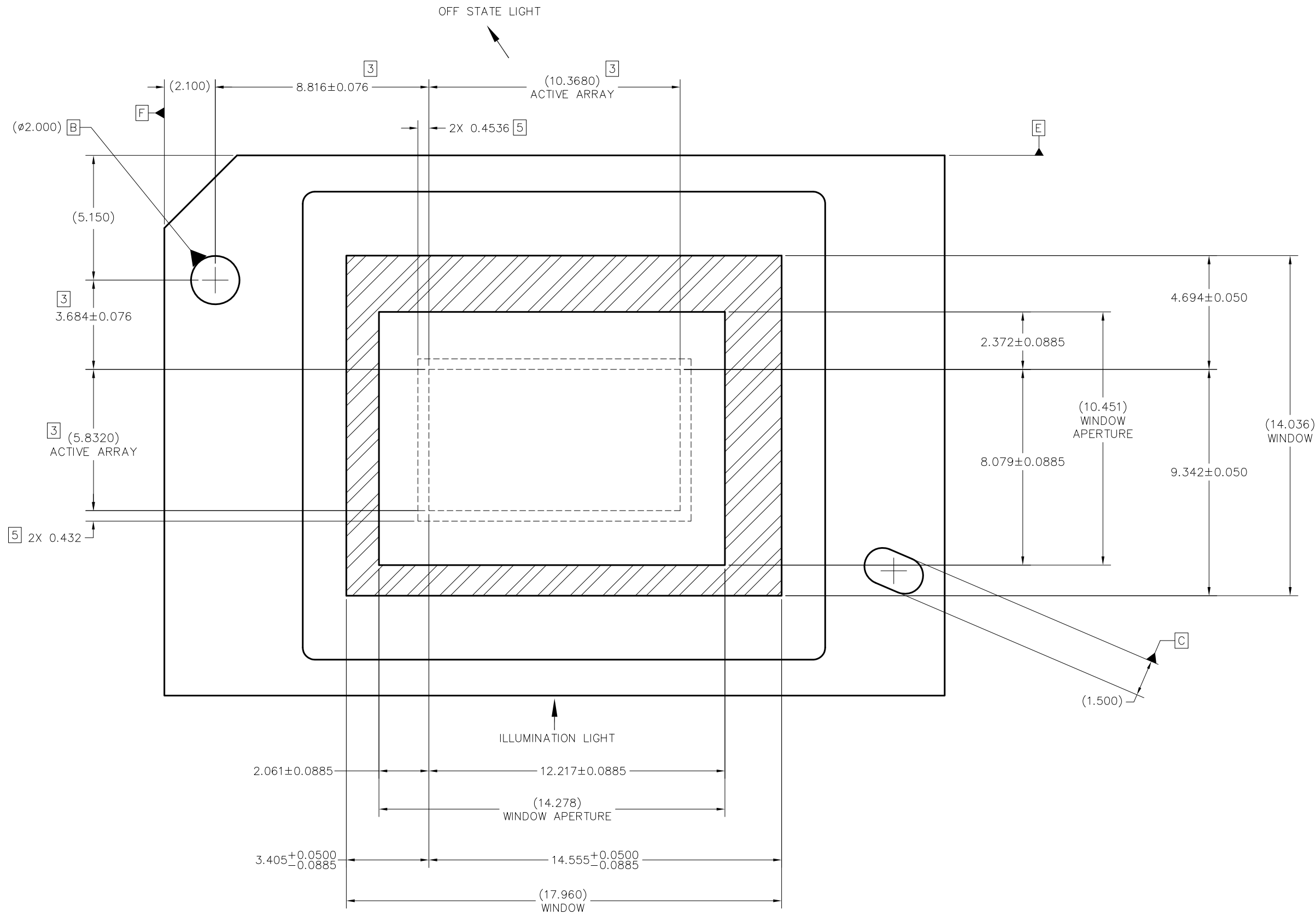
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4

3

DWG NO 2515168 SH 3

1



VIEW E (SHEET 1)
 DMD WINDOW AND ACTIVE ARRAY
 SCALE 12:1

 TEXAS INSTRUMENTS Dallas, Texas	DWN	DATE	SIZE	DRAWING NO	REV
	ISSUE DATE	SCALE 4/1	B	2515168	B
				SHEET 3	

ACED2c

8

7

6

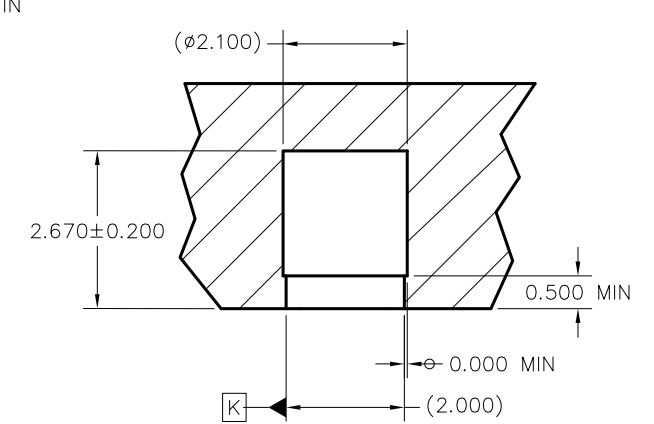
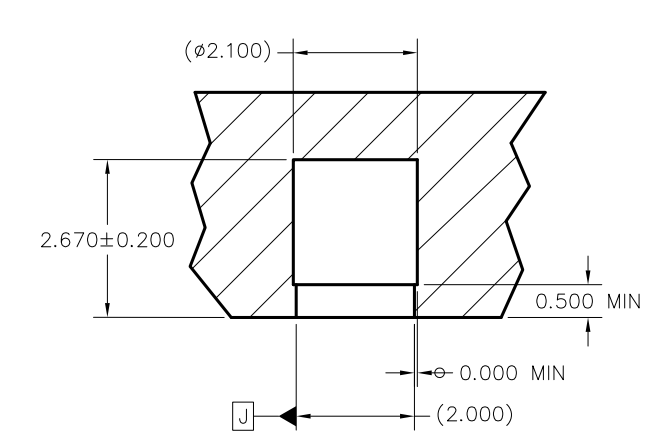
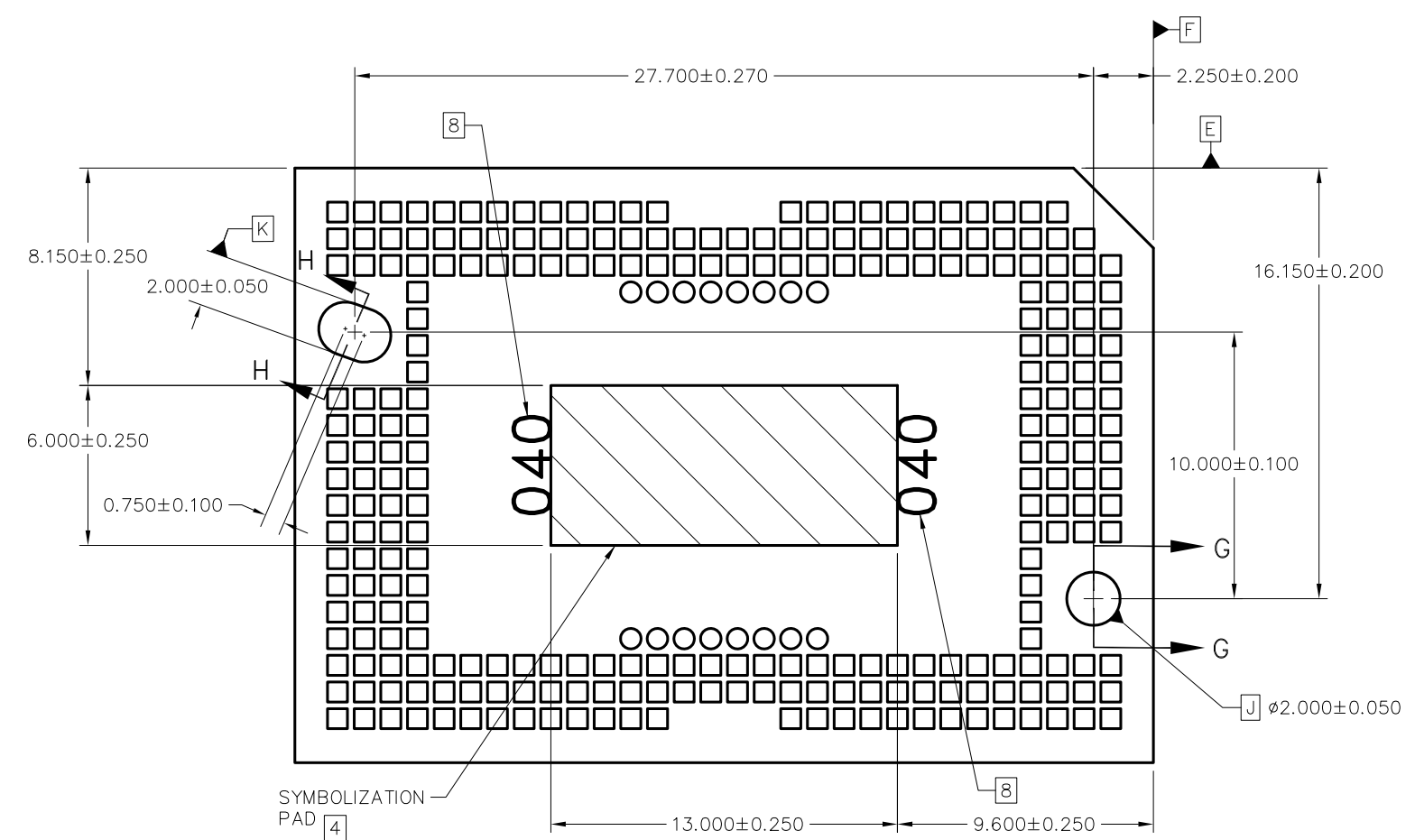
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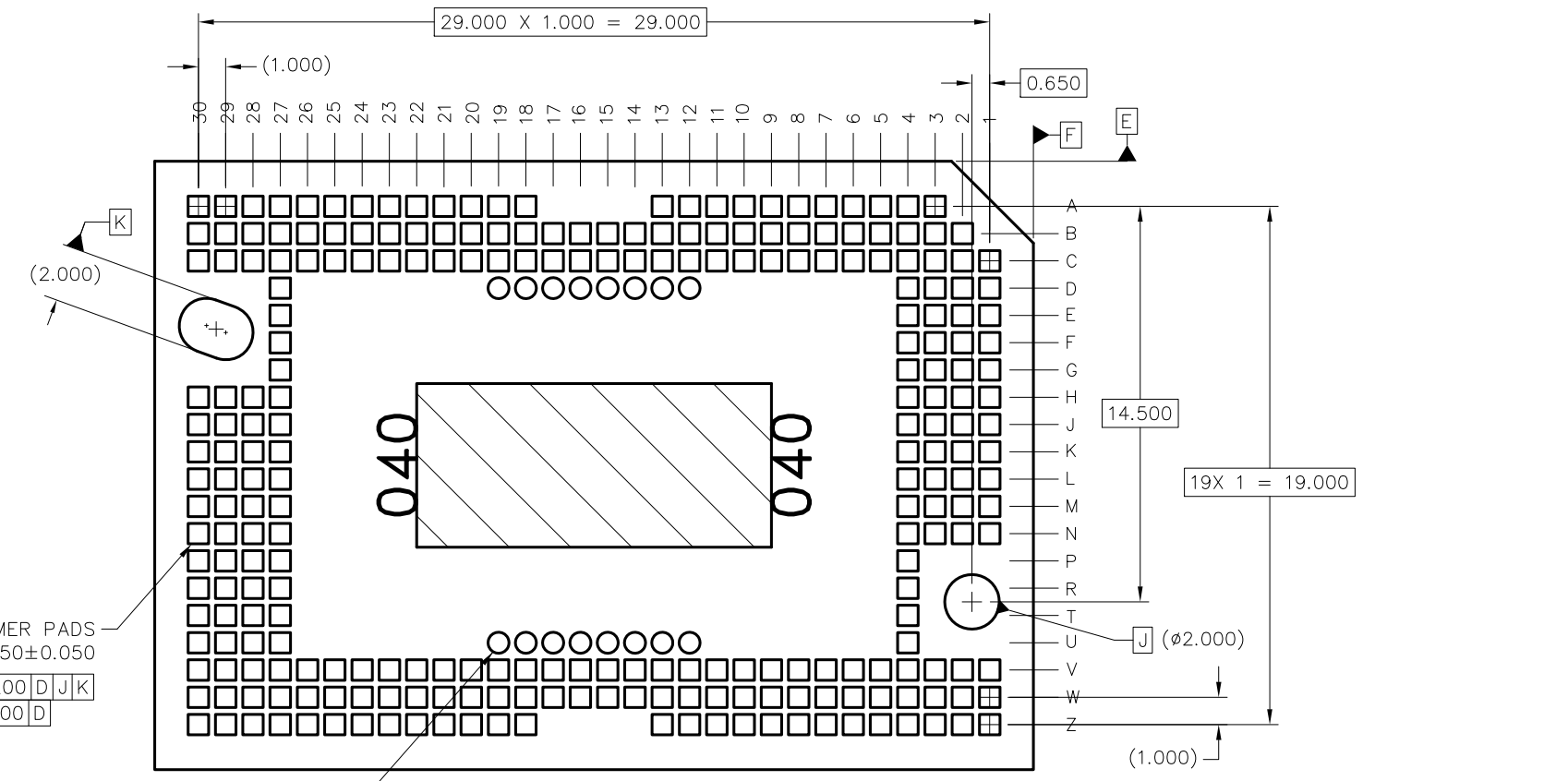
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2

1



VIEW F-F (SHEET 1)
DATUMS J AND K, SYMBOLIZATION PAD
SCALE 8/1



257X LGA CUSTOMER PADS
0.750±0.050 X 0.750±0.050

ø	0.200	D	J	K
	0.100	D		

16X LGA TEST PADS
DO NOT CONNECT

VIEW J-J (SHEET 1)
LGA PADS
SCALE 8/1

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